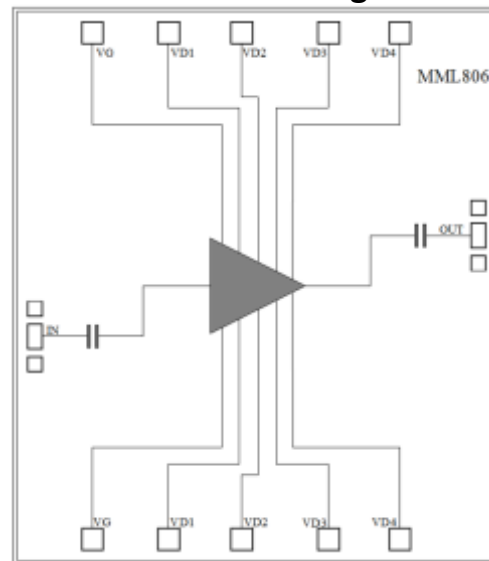


Features

- Frequency : 0-10GHz
- Small Signal Gain : 15dB Typical
- Gain Flatness : ± 2.5 dB Typical
- Noise Figure : 4.5dB Typical
- P1dB : 12dBm Typical
- Power Supply : VD=+4V@119mA ,VG=-0.4V
- Input/Output : 50 Ω
- Chip Size : 1.766 x 2.0 x 0.05mm

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Functional Block Diagram

Electrical Specifications

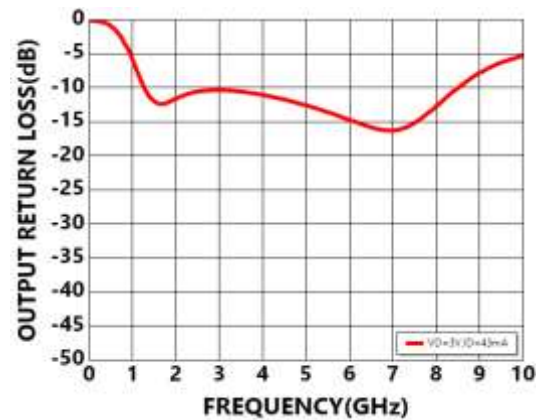
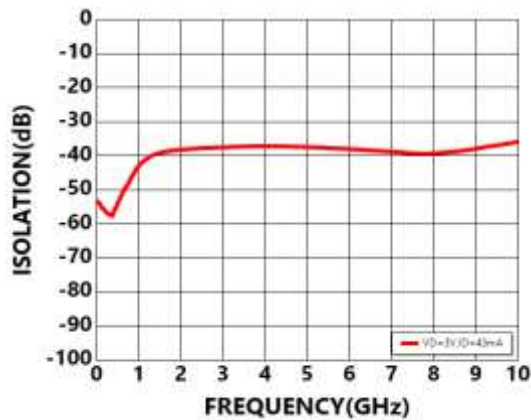
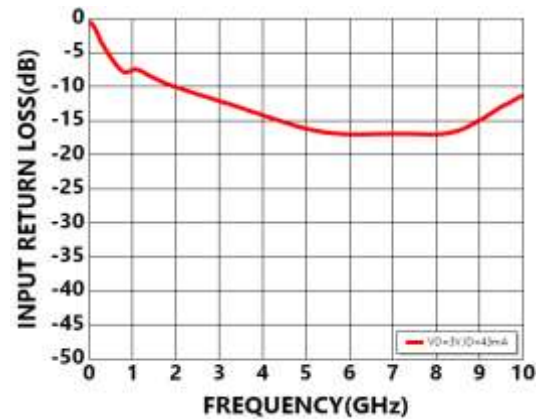
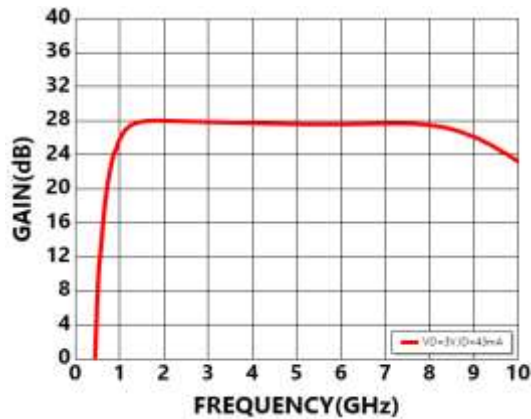
TA = +25°C, VD=4V,ID=67mA Typical

Parameter	Min.	Type.	Max.	Min.	Type.	Max.	Unit
Frequency		0 - 5			5 - 10		GHz
Small Signal Gain	-51.7	-11.3	29.2	24.5	26.7	29.0	dB
Gain Flatness		± 45.0			± 1.9		dB
Noise Figure	0.6	1.0	1.4	0.7	0.9	1.1	dB
P1dB - Output 1dB Compression	9.4	13.8	18.3	15.5	16.5	17.6	dBm
Psat - Saturated Output Power	16.7	17.7	18.6	18.5	19.0	19.5	dBm
OIP3 - Output Third Order Intercept	20.5	25.2	29.9	26.9	28.4	29.9	dBm
Input Return Loss	-19.1	-9.8	-0.5	-21.1	-16.6	-12.2	dB
Output Return Loss	-13.1	-6.6	-0.1	-20.0	-12.9	-5.9	dB



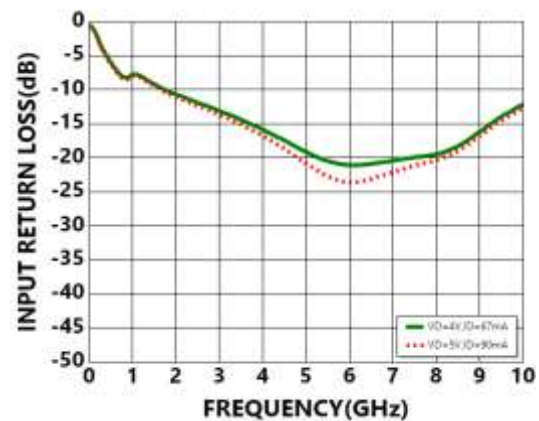
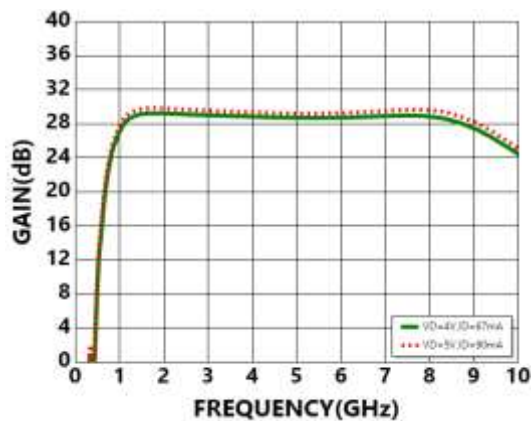
Measurement Plots: S-parameters

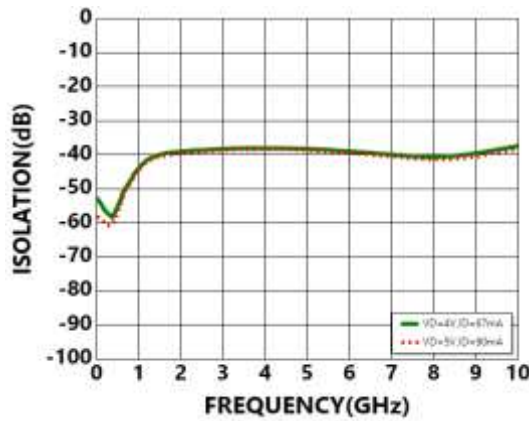
VD=4V, ID=67mA



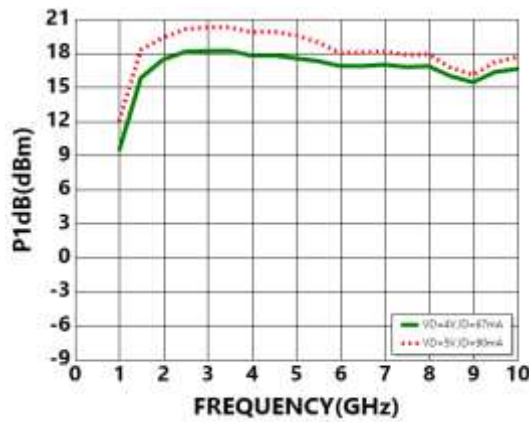
Measurement Plots: S-parameters

TA = +25°C

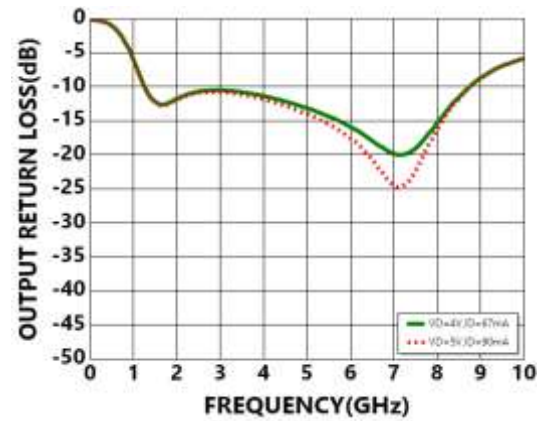
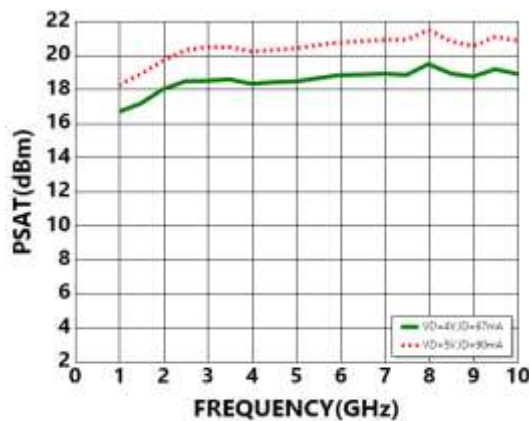




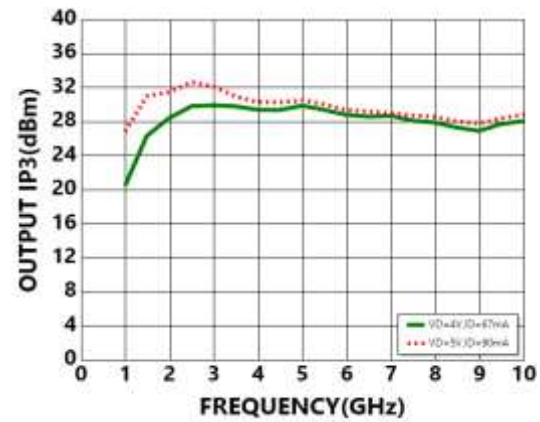
Measurement Plots: P1dB
TA = +25°C



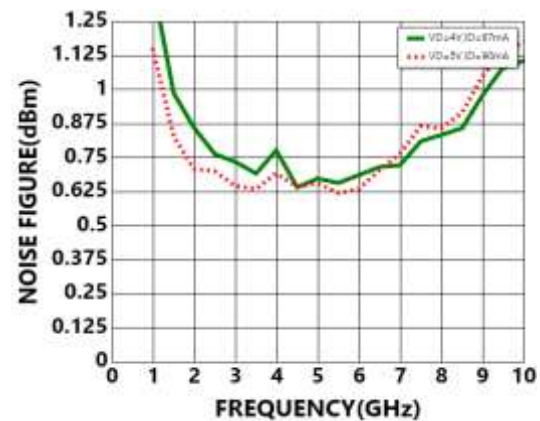
Measurement Plots: Psat
TA = +25°C

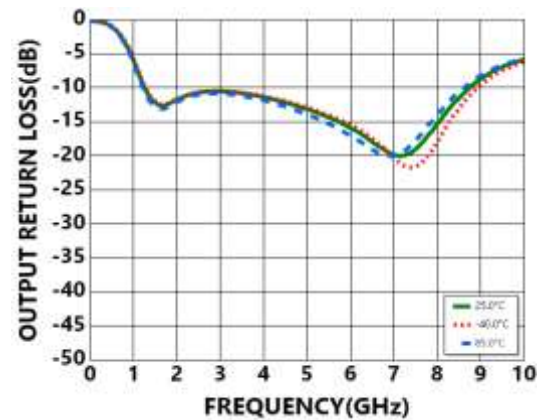
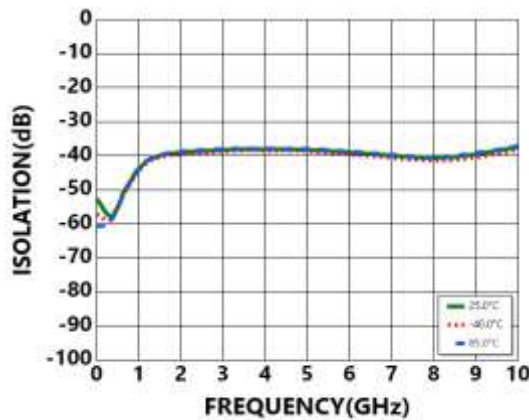
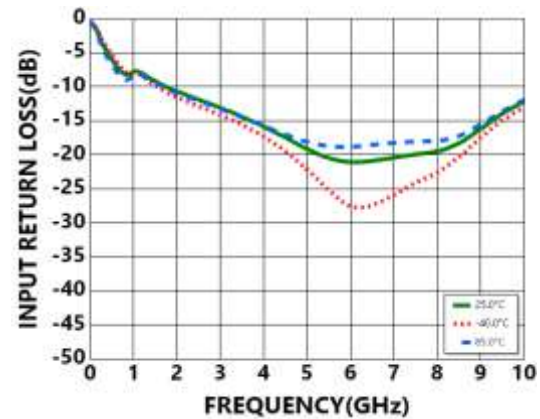
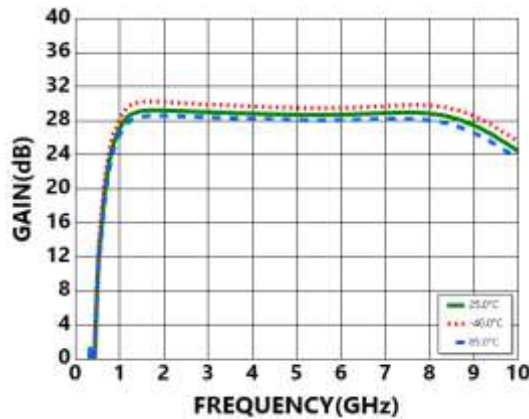
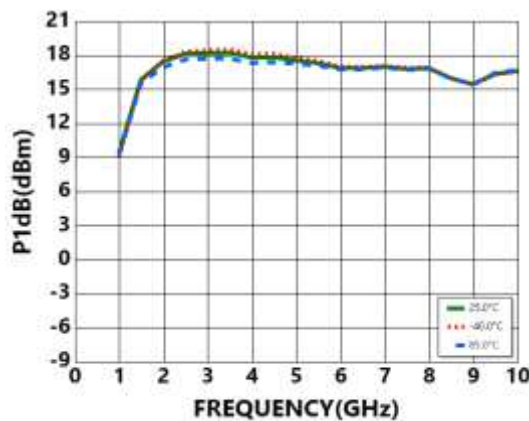
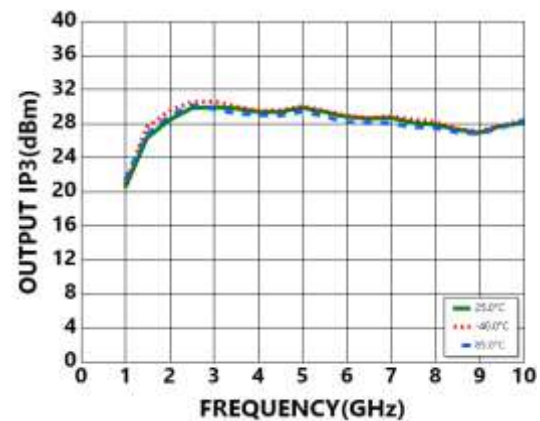


Measurement Plots: OIP3
TA = +25°C

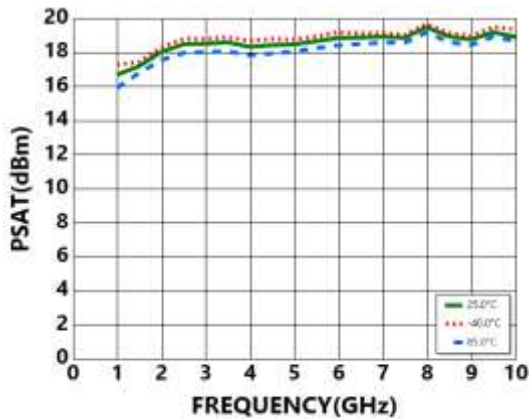


Measurement Plots: Noise Figure
TA = +25°C

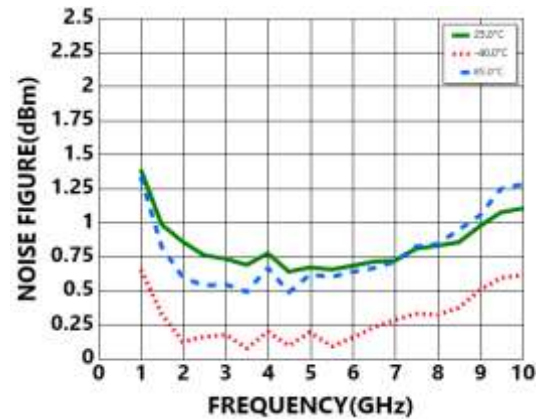


Measurement Plots: S-parameters
VD=4V, ID=67mA

Measurement Plots: P1dB
VD=4V, ID=67mA

Measurement Plots: OIP3
VD=4V, ID=67mA


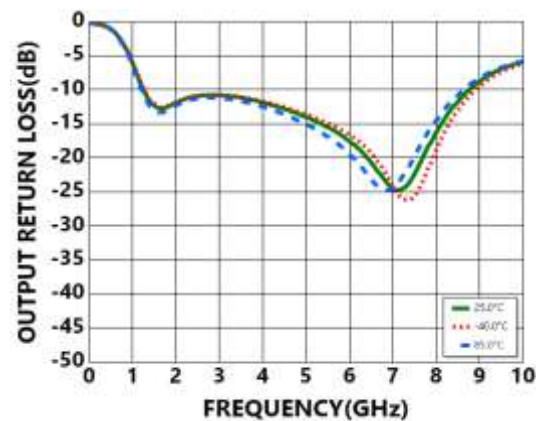
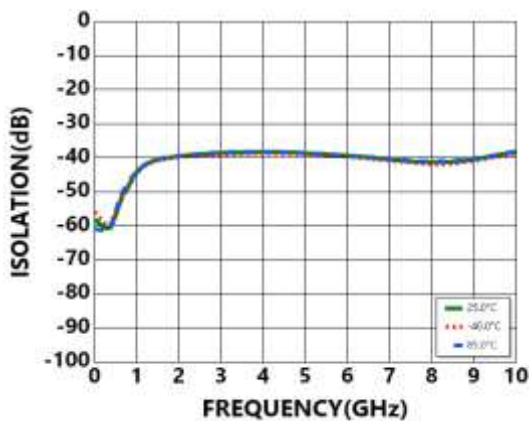
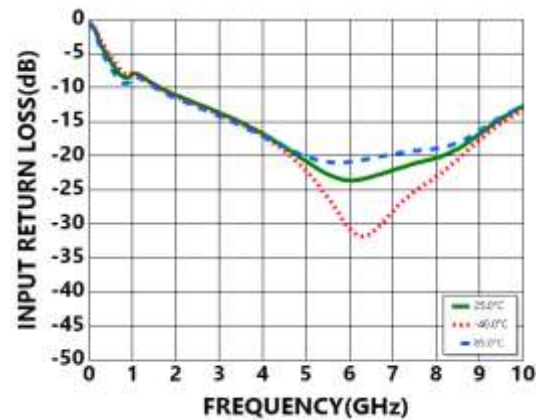
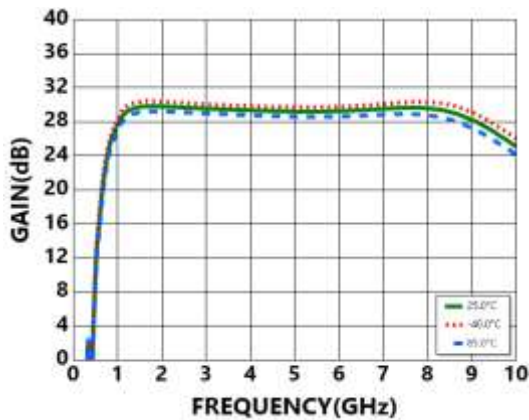
Measurement Plots: Psat
VD=4V, ID=67mA



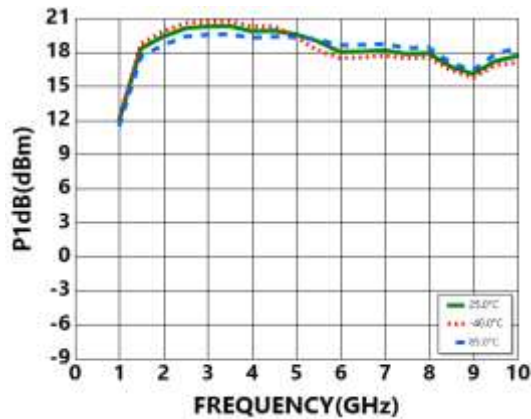
Measurement Plots: Noise Figure
VD=4V, ID=67mA



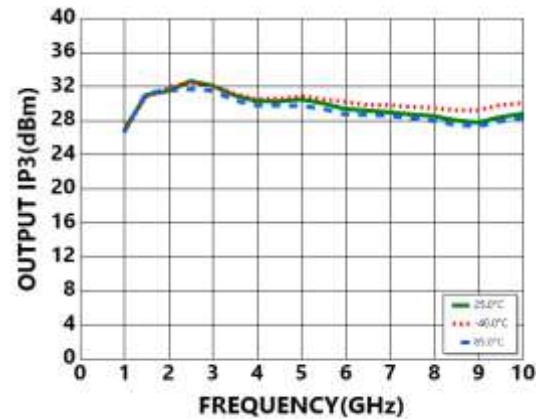
Measurement Plots: S-parameters
VD=5V, ID=90mA



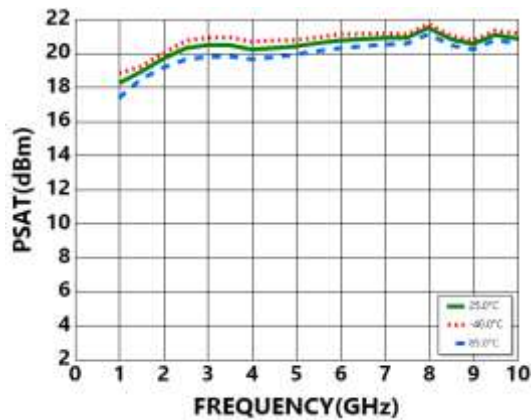
Measurement Plots: P1dB
VD=5V, ID=90mA



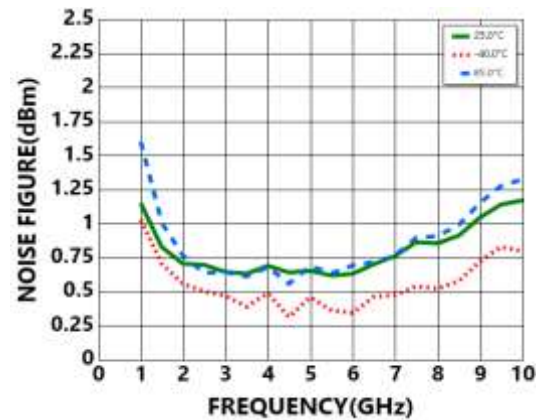
Measurement Plots: OIP3
VD=5V, ID=90mA



Measurement Plots: Psat
VD=5V, ID=90mA



Measurement Plots: Noise Figure
VD=5V, ID=90mA



Absolute Maximum Ratings

Drain Bias Voltage (VD)	+4.5V
Gate Bias Voltage (VG)	-2V to 0V
RF Input Power (RFIN)	+15dBm
Continuous P _{diss} (T = 85 °C) (derate 6.1mW/°C above 85 °C)	175°C
Thermal Resistance (channel to die bottom)	0.55W
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C

Typical Supply Current

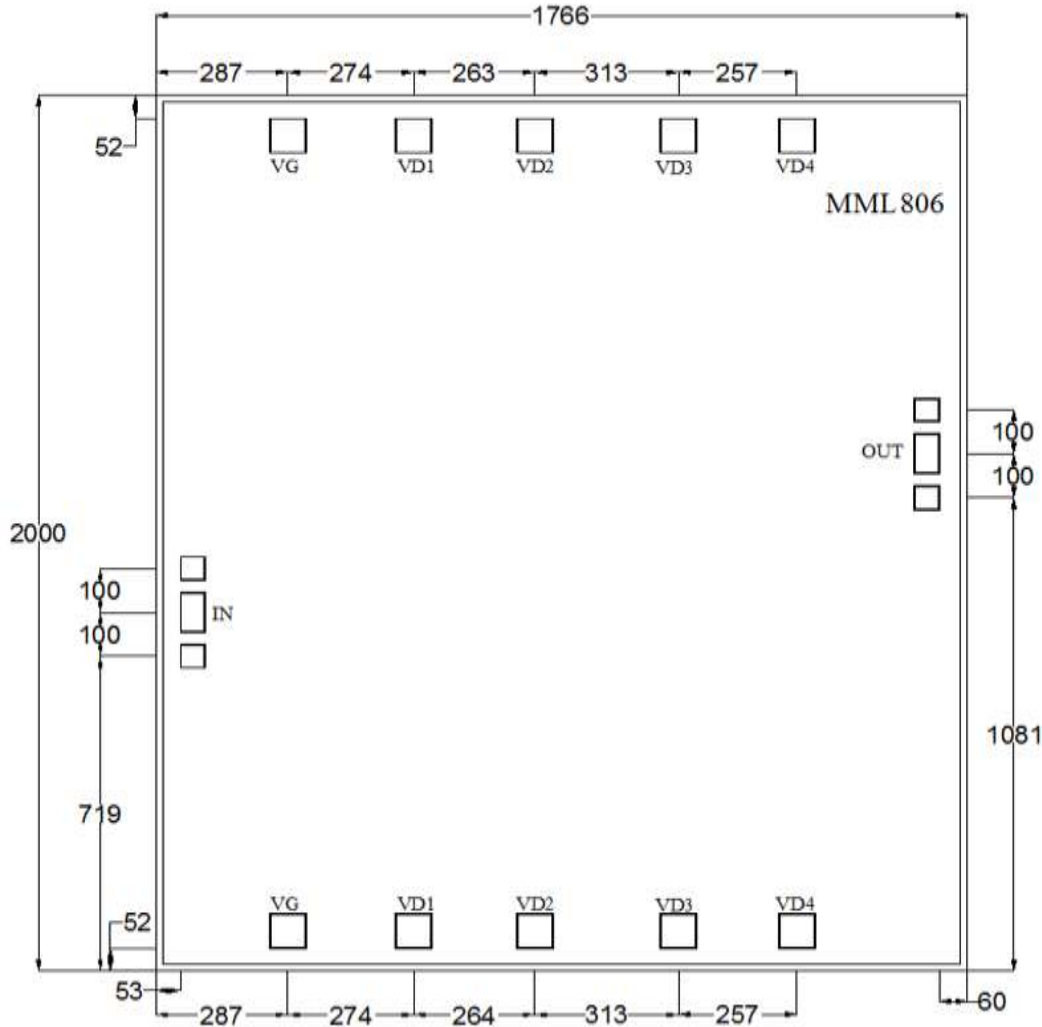
VD(V)	VG(V)	IDQ(mA)
+3.5	-0.38	118
4.0	-0.40	119
4.0	-0.50	71



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**



Outline Drawing:
All Dimensions in μm

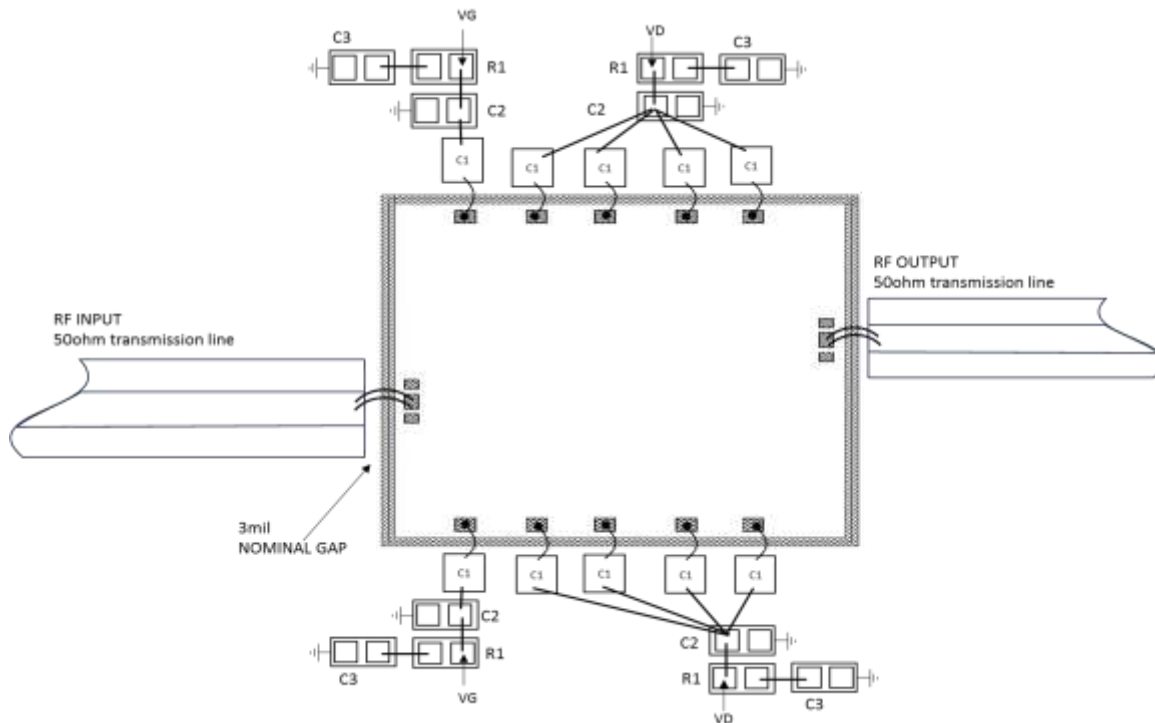


Notes:

1. Die thickness: $50\mu\text{m}$
2. VD bond pad is $75*75\mu\text{m}^2$
3. VG bond pad is $75*75\mu\text{m}^2$
4. RF IN/OUT bond pad is $50*86\mu\text{m}^2$
5. Bond pad metalization: Gold
6. Backside metalization: Gold

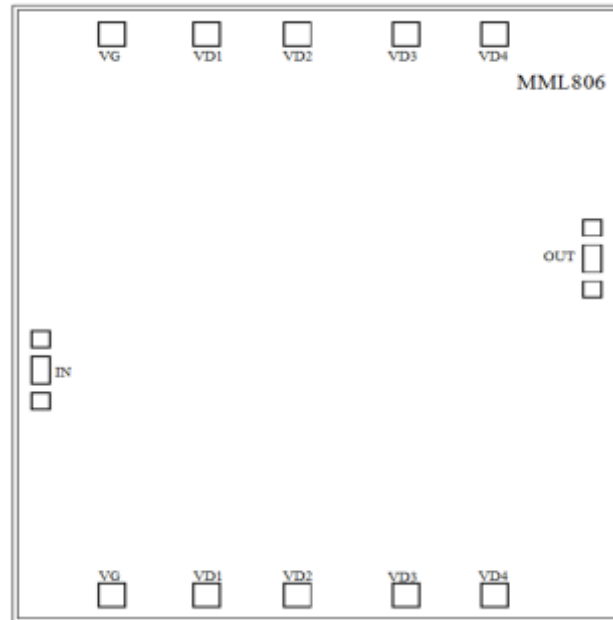


Assembly Drawing



Item	Description
C1	100pF Example: Skyworks Part: SC10002430
C2	0.01μF Example: TDK Part:C1005X7R1H103K050BB (0402)
C3	0.1μF Example: TDK Part:C1005X7R1H104K050BB (0402)
R1	100Ω Example: Yageo Part:SR0402FR-7T10RL

Item	Funciton	Description
1	RF IN	RF signal input terminal; no blocking capacitor required.
2	RF OUT	RF signal output terminal; no blocking capacitor required.
3	VD	Drain Biases for the Amplifier ; An external biasing circuit is required.
4	VG	Gate Biases for the Amplifier ; An external biasing circuit is required.
5	Die Bottom	Die bottom must be connected to RF and dc ground.



Biasing and Operation

Turn ON procedure:

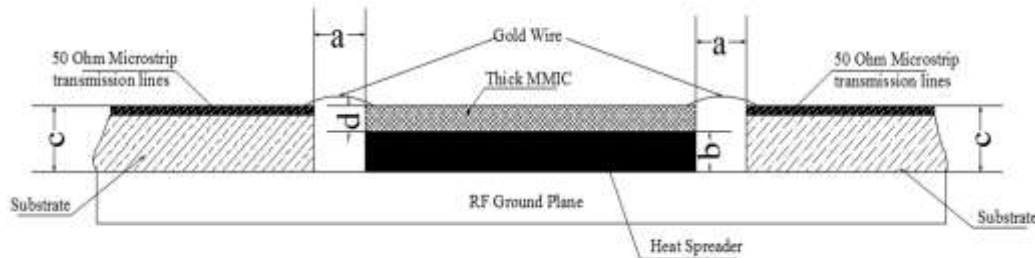
1. Connect GND to RF and dc ground.
2. Set the gate bias voltages VG to -2V.
3. Set the drain bias voltages VD to +4V.
4. Apply RF signal.

Turn OFF procedure:

1. Turn off the RF signal.
2. Decrease the gate bias voltages, VG to -2V to achieve a IDQ = 0 mA (approximately).
3. Decrease the drain bias voltages to 0 V.
4. Increase the gate bias voltages to achieve a quiescent supply current of 82 mA.
5. Increase the all gate bias voltages to 0 V.



Mounting & Bonding Techniques for MMICs



Direct Mounting

1. Typically, the die is mounted directly on the ground plane.
2. If the thickness difference between the substrate (thickness c) and the die (thickness d) exceeds 0.05 mm (i.e., $c - d > 0.05$ mm), it is recommended to first mount the die on a heat spreader, then attach the heat spreader to the ground plane.
3. Heat Spreader Material: Molybdenum-copper (MoCu) alloy is commonly used.
4. Heat Sink Thickness (b): Should be within the range of $(c - d - 0.05$ mm) to $(c - d + 0.05$ mm).
5. Spacing (a): The gap between the bare die and the 50 Ω transmission line should typically be 0.05 mm to 0.1 mm. If the application frequency is higher than 40GHz, then this gap is recommended to be 0.05mm

Wire Bonding Interconnection

The connection between the die and the 50 Ω transmission line is usually made using 25 μ m diameter gold (Au) wires, bonded via wedge bonding or ball bonding processes.

Die Attachment Methods

1. Conductive Epoxy:

After adhesive application, cure according to the manufacturer's recommended temperature profile.

2. Au-Sn80/20 Eutectic Bonding:

Use preformed Au-Sn80/20 solder preforms.

Perform bonding in an inert atmosphere (N_2 or forming gas: 90% N_2 + 10% H_2).

Keep the time above 320°C to less than 20 seconds to prevent excessive intermetallic formation.

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